Sample Geometry Effect on Mechanical Property of **Electrodeposited Gold Evaluated by Micro-Bending Tes** 

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## Experimental

#### **Electroplating of gold**

Electrolyte	Sulfite-based (10 g/L of gold)
Cathode	9M HCI treated titanium plate
Anode	Platinum plate
Current density	5 mA/cm <sup>2</sup>
Time	80 min

Average grain size measured by EBSD : 1.1~1.3µm

Stress-strain curve for the bending test

# FIB (Focus Ion Beam)



#### **Micro-mechanical test**





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#### **Results and Discussion**



### Conclusion

· Micro bending test was conducted on electroplated gold cantilever with different width and thickness.

The size effect appeared in the thickness direction, which is parallel to the loading direction, and did not appear in the width direction, which is perpendicular to loading direction.

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